

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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LI0805H750R-10

UNCONTROLLED DOCUMENT

PHYSICAL DIMENSIONS:

100

20

IMPEDANCE

MPEDANCE

A 2.00 [.079] ± 0.20 [.008]

1.25 [.049] ± 0.20 [.008]

C 0.90 [.035] ± 0.20 [.008]

D 0.51 [.020] ± 0.25 [.010]

Z vs FREQUENCY

IMPEDANCE UNDER DC BIAS

1.47 [.058]



LAND PATTERNS FOR REFLOW SOLDERING

0.66

.026]

ORIGINAL DRAFT

DESCRIPTION

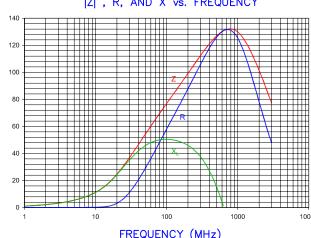
ELECTRICAL CHARACTERISTICS:										
Z @ 100MHz (Ω)		DCR $\left(\begin{array}{c}\Omega\end{array}\right)$	Rated Current							
Nominal	75									
Minimum	56									
Maximum	94	0.15	800 mA							

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
- 2. TERMINATION FINISH IS 100% TIN.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. OPERATING TEMP. RANGE: -40°C~+125°C. (INCLUDING SELF-HEATING)

FREQUENCY (MHz)

|Z| , R, AND X vs. FREQUENCY



(For wave soldering, add 0.762 [.030] to this dimension.)

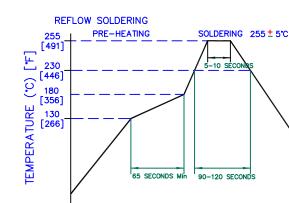
3.23

Α

RECOMMENDED SOLDERING CONDITIONS

NATURAL COOLING

2 of 2



LI0805H750R-10-D

DIMENSIONS ARE IN mm [INCHES].				This print is the property of Lair	d			
				Tech. and is loaned in confidence subject to return upon request a	nd I	I _	=	.■"
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				copies shall be made without the	:	LŲ	▮ ▮ ₹	
				written consent of Laird Tech. Al rights to design or invention are	' _			
				reserved.				
Ъ	ADD OPERATING TEMPERATURE	08/05/13	QU	PROJECT/PART NUMBER:	REV	PART TO	PE:	DRAWN BY:
	UPDATE LAIRD LOGO AND REFLOW CURVE			LI0805H750R-10	ΙD	CO-	-FIRE	ТМВ
С		03/04/10			1	- 00	CO-FIRE	
В	UPDATE COMPANY LOGO ADD ROHS SYM	07/21/08	JRK	DATE: 04/05/04 S	CALE:	NTS	SHEET:	

04/05/04 TMB

AGILENT E4991A RF Impedance/Material Analyzer HP 16194A Test Fixture. TEST REF. 3235